AMENDMENTS TO THE CLAIMS:

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

LISTING OF THE CLAIMS:

1-10. (Canceled).

11. (Canceled).

12. (Canceled).

13-17. (Canceled).

18. (Previously Presented) A method for manufacturing a converter module comprising:

providing a positive terminal, a negative terminal, a phase terminal, a first semiconductor chip and a second semiconductor chip, at least one of the positive terminal, the negative terminal, and the phase terminal having a contact plate, a bar-shaped terminal lug, and an auxiliary element, the terminal lug being positioned asymmetrically on the contact plate, the auxiliary element preventing the terminal from tilting about a longitudinal axis of the bar-shaped terminal lug, wherein the phase terminal is structurally shaped identically to one of the positive terminal or the negative terminal;

stacking the positive terminal, the negative terminal, the phase terminal, the first semiconductor chip and the second semiconductor chip on top of one another in a joining device, the phase terminal being situated rotated by 180° about the longitudinal axis of the terminal lug in relation to an orientation of the phase terminal that would be identical to an orientation of one of the structurally identically shaped positive terminal or the structurally identically shaped negative terminal; and

encapsulating the stack in an injection molded housing.

19. (Previously Presented) The method as recited in claim 18, wherein at least one of the positive terminal, the negative terminal and the phase terminal is positioned in the joining device using an aperture provided in the auxiliary element.

20. (Previously Presented) The method as recited in claim 18, wherein the positive terminal or the negative terminal and the phase terminal are identical parts which are inserted into the joining device rotated by 180°.

21. (Previously Presented) The method as recited in claim 18, wherein the bar-shaped terminal lug is situated offset with respect to a plane created by the contact plate, and wherein at least two of the positive terminal, the negative terminal, and the phase terminal includes a respective bar-shaped terminal lug, each bar-shaped terminal lug being situated offset so that the respective terminal lugs may be brought out from the converter module on a same level.

22. (Previously Presented) The method as recited in claim 18, wherein the converter module is situated in an injection molded plastic housing.

23. (Previously Presented) The method as recited in claim 18, wherein the auxiliary element has a positioning aperture for positioning the auxiliary element in a joining device.

24. (Previously Presented) The method as recited in claim 18, wherein the bar-shaped terminal lug is situated offset with respect to a plane created by the contact plate, wherein at least two of the positive terminal, the negative terminal, and the phase terminal includes a respective bar-shaped terminal lug, each bar-shaped terminal lug being situated offset so that the respective terminal lugs may be brought out from the converter module on a same level, wherein the converter module is situated in an injection molded plastic housing, and wherein the auxiliary element has a positioning aperture for positioning the auxiliary element in a joining device.

25. (Previously Presented) The method as recited in claim 24, wherein at least one of the positive terminal, the negative terminal and the phase terminal is positioned in the joining device using an aperture provided in the auxiliary element.

26. (Previously Presented) The method as recited in claim 24, wherein the positive terminal or the negative terminal and the phase terminal are identical parts which are inserted into the joining device rotated by 180°.

27-31. (Canceled).

32. (Previously Presented) A single-phase converter module, comprising:

a positive terminal;

a negative terminal;

a phase terminal;

a first semiconductor chip; and

a second semiconductor chip;

wherein the positive terminal, the negative terminal, the phase terminal, the first semiconductor chip, and the second semiconductor chip are situated on top of one another in a stack, wherein a bar-shaped phase terminal lug of the phase terminal and a bar-shaped terminal lug of one of the positive terminal and the negative terminal extend in a same direction, and wherein the bar-shaped phase terminal lug and the bar-shaped terminal lug are adjacent to each other and extend alongside each other,

wherein the phase terminal and the one of the positive terminal and the negative terminal each include a contact plate, the bar-shaped terminal lug which is positioned asymmetrically on the contact plate, and an auxiliary element which prevents the at least one of the positive terminal, the negative terminal, and the phase terminal from tilting about a longitudinal axis of the terminal lug, the auxiliary element being able to be detached after the converter module is assembled, and

wherein the phase terminal is shaped identically to one of the positive terminal and the negative terminal.

33. (Previously Presented) The converter module as recited in claim 32, wherein the bar-shaped terminal lug is offset with respect to a plane created by the contact plate.

34. (Previously Presented) The converter module as recited in claim 33, wherein the bar-shaped phase terminal lug and the bar-shaped terminal lug are offset so that auxiliary element end of the bar-shaped phase terminal lug and the bar-shaped terminal lug lie in a same plane.

35. (Previously Presented) The converter module as recited in claim 32, wherein the converter module is situated in an injection molded plastic housing.

36. (Previously Presented) The converter module as recited in claim 32, wherein the auxiliary element has a positioning aperture for positioning the auxiliary element in a joining device.